



SOLDER ECOLOY TC

Lead-Free Alloy for Electronics

DESCRIPTION

Stannol Ecoloy TC (S-Sn99.3Cu0.7) is a lead-free solder according to DIN EN ISO 9453 (alloy no. 401) to eliminate tin-lead alloys in all processes of electric and electronic manufacturing. The use of Ecoloy TC guarantees that lead-free assemblies can be produced according to WEEE and RoHS.

Stannol Ecoloy TC eliminates problematic disposal of lead containing waste.

CHARACTERISTICS

Stannol Ecoloy TC offers the following advantages:

- pure tin-copper alloy - no other additions
- patent-free alloy – no licence fees
- eutectic alloy (Melting Point 227°C)
- good Wetting properties
- valuable price – no silver

APPLICATION

Using Ecoloy TC solder requires adaptation of machine settings. Temperature profiles must match with the high melting point of the alloy and the thermal demand of the PCB. The properties of solder joints manufactured with ECOLOY® TC are comparable with those soldered with tin-lead alloys. This alloy can be used for wave soldering as well as for dip tinning e.g. for wire beads.

PHYSICAL AND MECHANICAL PROPERTIES OF LEAD-FREE ECOLOY SOLDERS COMPARED WITH S-Sn63Pb37:

GENERAL PROPERTIES	S-Sn63Pb37*	Stannol Ecoloy TSC (S-Sn95.5Ag3.8Cu0.7)*	Stannol Ecoloy TS (S-Sn96.3Ag3.7)*	Stannol Ecoloy TC (S-Sn99.3Cu0.7)*
Melting point, °C:	183	217	221	227
Electrical Conductivity, %IACS:	11.9	13	14	15.6
Electrical Resistivity, μΩcm:	14.5	13	12.3	12.6
Brinell Hardness, HB:	17	15	15	9
Density, g/cm³:	8.4	7.5	7.5	7.3
Shear tension, (20°C)/N mm⁻² at 0,004 s⁻¹ shear rate:	40	48	58	48
Shear resistance N mm⁻² at 0,1mm⁻¹, 20°C:	23	27	27	27
at 0,1mm⁻¹, 100°C:	14	17	17	17
Creep resistance* N mm⁻² 20°C:	3.3	13.0	13.7	13.0
100°C:	1.0	5.0	5.0	5.0

*Complying with DIN EN ISO 9453

RECOMMENDED CONDITIONS OF USE

Wave soldering: The use of Ecoloy TC Solder requires a soldering temperature of about 260 to 280°C. Optimum conditions must be found out depending on the type of PCB. The application of additional Inertgas is very helpful. The absence of Oxygen and oxides on the solder surface will enhance the wetting of the solder and when leaving the solder wave no excessive solder will remain on the solder joint. Inertgas will reduce the formation of bridges and icicles. The formation of dross will be reduced enormously.

Liquid flux for wave soldering: In principle all common fluxes like Stannol EF350 are suitable for lead-free soldering. The solid content should not be as low as for tin-lead, because due to the high thermal demand of the PCB there is more preheat and higher solder bath temperature necessary. Therefore stability and sustainable activity is of importance. As a complete ecological solution the use of VOC-free liquid fluxes should be an option, e.g. Stannol WF300S. Because the solvent is water, all process requirements have to be adapted to the specific properties of the flux.

Rework and Repair: All temperature profiles used for tin-lead have to be changed to new requirements of the lead-free alloys (melting point +44°C). If components are still with tin-lead coating, solder joint properties will become less reliable than completely lead free.

SUPPLY FORMS

Solder Wire (solid and flux cored)
Triangular bars
Kg-bars
Ingots with hanging hole

HEALTH AND SAFETY

Before using please read the material safety data sheet carefully and observe the safety precautions described.

NOTICE

The above values are typical and represent no form of specification. The Data Sheet serves for information purposes. Any verbal or written advise is not binding for the company, whether such information originates from the company offices or from a sales representative. This is also in respect of any protection rights of third parties, and does not release the customer from the responsibility of verifying the products of the company for suitability of use for the intended process or purpose. Should any liability on the part of the company arise, the company will only indemnify for loss or damage to the same extent as for defects in quality.